CD74HCx4067 High-Speed CMOS Logic 16-Channel Analog Multiplexer and Demultiplexer

1 Features

- Wide analog input voltage range
- Low ON resistance
  - V_{CC} = 4.5V, 70Ω (typ)
  - V_{CC} = 6V, 60Ω (typ)
- Fast switching and propagation speeds
- Break-before-make switching
  - 6ns (typ) at 4.5V
- Available in both narrow- and wide-body plastic packages
- Fanout (over-temperature range)
  - Standard outputs: 10 LSTTL loads
  - Bus driver outputs: 15 LSTTL loads
- Wide operating temperature range: –55°C to +125°C
- Balanced propagation delay and transition times
- Significant power reduction compared to LSTTL logic ICs
- HC types
  - 2V to 6V operation
  - High noise immunity: N_{IL} = 30%, N_{IH} = 30% of V_{CC} at V_{CC} = 5V
- HCT types
  - 4.5V to 5.5V operation
  - Direct LSTTL input logic compatibility, V_{IL}= 0.8V (max), V_{IH} = 2V (min)
  - CMOS input compatibility, $I_I \leq 1\mu A$ at V_{OL}, V_{OH}

2 Applications

- Energy infrastructure
- Building automation
- Wireless infrastructure
- Appliances
- Data center & enterprise computing
- Retail automation & payment
- Signal gating
- Modulators
- Squelch controls
- demodulators
- choppers
- commutating switches
- Analog-to-digital and digital-to-analog conversions
- Digital control of frequency, impedance, phase, and analog-signal gain

3 Description

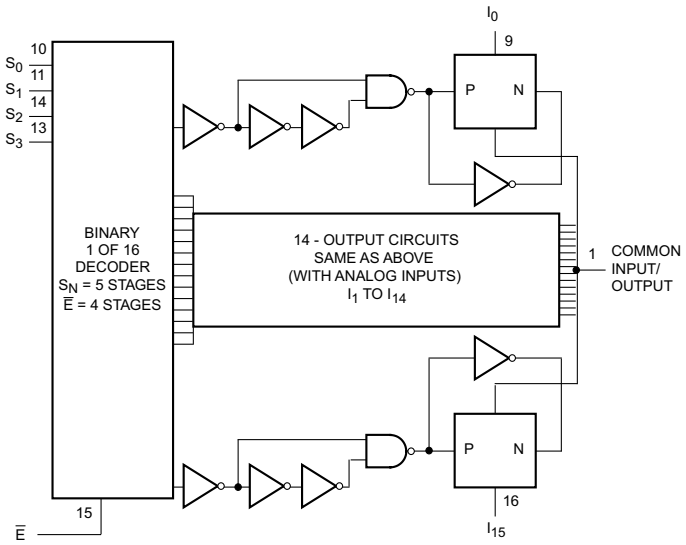
The CD74HC4067 and CD74HCT4067 devices are digitally controlled analog switches that use silicon-gate CMOS technology to achieve operating speeds similar to LSTTL, with the low power consumption of standard CMOS integrated circuits.

These analog multiplexers and demultiplexers control analog voltages that may vary across the voltage supply range. They are bidirectional switches, thus allowing any analog input to be used as an output and vice-versa. The switches have low *on* resistance and low *off* leakages. In addition, these devices have an enable control that, when high, disables all switches to their *off* state.

Package Information

PART NUMBER	PACKAGE (1)	BODY SIZE (NOM)
CD74HC4067M	SOIC(24)	15.4mm × 10.3mm
CD74HC4067M96	SOIC(24)	15.4mm × 10.3mm
CD74HC4067SM96	SSOP(24)	8.20mm × 7.40mm
CD74HCT4067M	SOIC(24)	15.4mm × 10.3mm
CD74HC4067PW	TSSOP(24)	7.8mm × 6.4mm
CD74HCT4067PW	TSSOP(24)	7.8mm × 6.4mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Functional Block Diagram

Table of Contents

4 Pin Configuration and Functions

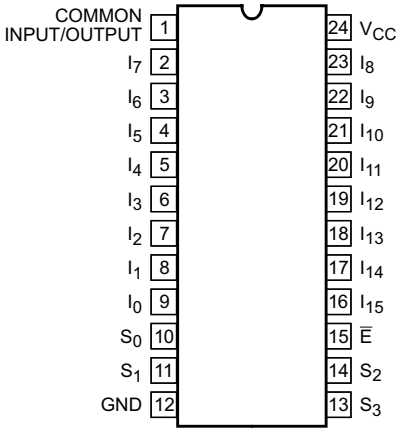


Figure 4-1. N, DW, or DB Packages 24-Pin PDIP, SOIC, or SSOP (Top View)

PIN		TYPE(1)	DESCRIPTION
NAME	NO.		
COMMON INPUT/ OUTPUT	1	IO	Common input or output.
I_7	2	IO	Switch input/output
I_6	3	IO	Switch input/output
I_5	4	IO	Switch input/output
I_4	5	IO	Switch input/output
I_3	6	IO	Switch input/output
I_2	7	IO	Switch input/output
I_1	8	IO	Switch input/output
I_0	9	IO	Switch input/output
S_0	10	I	Select/Address pin
S_1	11	I	Select/Address pin
GND	12	P	Ground pin
S_3	13	I	Select/Address pin
S_2	14	I	Select/Address pin
$\overline{E}$	15	I	Enable for all switches ON/OFF
I_{15}	16	IO	Switch input/output
I_{14}	17	IO	Switch input/output
I_{13}	18	IO	Switch input/output
I_{12}	19	IO	Switch input/output
I_{11}	20	IO	Switch input/output
I_{10}	21	IO	Switch input/output
I_9	22	IO	Switch input/output
I_8	23	IO	Switch input/output
V_{CC}	24	P	Power pin

(1) I = input, O = output, P = Power

4.1 Device Functional Modes

Table 4-1. Truth Table

S0	S1	S2	S3	$\overline{E}$	SELECTED CHANNEL
X	X	X	X	1	None
0	0	0	0	0	0
1	0	0	0	0	1
0	1	0	0	0	2
1	1	0	0	0	3
0	0	1	0	0	4
1	0	1	0	0	5
0	1	1	0	0	6
1	1	1	0	0	7
0	0	0	1	0	8
1	0	0	1	0	9
0	1	0	1	0	10
1	1	0	1	0	11
0	0	1	1	0	12
1	0	1	1	0	13
0	1	1	1	0	14
1	1	1	1	0	15

5 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1) (2)

			MIN	MAX	UNIT
V_{CC} HC	DC Supply voltage		-0.5	7	V
V_{CC} HCT			–0.5	7	V
I_{IK}	DC input diode current	For V_I < -0.5V or V_I > V_{CC} + 0.5V	–20	20	mA
I_{OK}	DC output diode current	For V_O < -0.5V or V_O > V_{CC} + -0.5V	–20	20	mA
I_{CC}	DC V_{CC} or ground current		–50	50	mA
DC Output Source or Sink Current per Output Pin, I_O	For V_O > -0.5V or V_O < V_{CC} + -0.5V		–25	25	mA
T_{JMAX}	Maximum junction temperature (Plastic Package)			150	°C
T_{stg}	Storage temperature		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to ground, unless otherwise specified.

6 Thermal Information

THERMAL METRIC (1)		CD74HCx4067				UNIT
		E (PDIP)	M (SOIC)	SM (SSOP)	PW (TSSOP)	
		24 PINS	24 PINS	24 PINS	24 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	67	84.8	96.2	97.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	N/A	57.0	60.0	45.0	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	N/A	59.5	65.1	62.7	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	N/A	29.0	21.1	5.20	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	N/A	59.0	64.4	62.1	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

7 Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage range (T_A = full package temperature range)(2)	CD54 and 74HC types	2		6	V
		CD54 and 74HCT types	4.5		5.5	
V_{IS}	Analog switch I/O voltage		0		V_{CC}	V
T_A	Ambient temperature		–55		125	°C
t_r , t_f	Input rise and fall times	2 V	0		1000	ns
		4.5 V	0		500	
		6 V	0		400	

8 Electrical Characteristics: HC Devices

Over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS				MIN	TYP	MAX	UNIT
Analog Switch									
		V_{IS} (V)	V_I (V)	V_{CC} (V)	T_A				
High Level Input Voltage	V_{IH}			2	25°C	1.5			V
					–40°C to +85°C	1.5			
					–55°C to +125°C	1.5			
				4.5	25°C	3.15			
					–40°C to +85°C	3.15			
					–55°C to +125°C	3.15			
				6	25°C	4.2			
					–40°C to +85°C	4.2			
					–55°C to +125°C	4.2			
Low Level Input Voltage	V_{IL}			2	25°C			0.5	V
					–40°C to +85°C			0.5	
					–55°C to +125°C			0.5	
				4.5	25°C			1.35	
					–40°C to +85°C			1.35	
					–55°C to +125°C			1.35	
				6	25°C			1.8	
					–40°C to +85°C			1.8	
					–55°C to +125°C			1.8	
"ON" Resistance IO = 1mA	R_{ON}	V_{CC} or GND	V_{CC} or GND	4.5	25°C		70	160	Ω
					–40°C to +85°C			200	
					–55°C to +125°C			240	
				6	25°C		60	140	
					–40°C to +85°C			175	
					–55°C to +125°C			210	
		V_{CC} to GND	V_{CC} to GND	4.5	25°C		90	180	Ω
					–40°C to +85°C			225	
					–55°C to +125°C			270	
				6	25°C		80	160	
					–40°C to +85°C			200	
					–55°C to +125°C			240	
"ON" Resistance Between Any Two Switches	ΔR_{ON}			4.5	25°C		10		Ω
				6			8.5		
Off-Switch Leakage Current	I_Z	$\overline{E}$ = V_{CC}	V_{CC} or GND	6	25°C			±0.8	μA
					–55°C to 85°C			±8	
					–55°C to 125°C			±8	
Input Leakage Current (Any Control)	I_{IL}		V_{CC} or GND(1)	6	25°C			±0.1	μA
					–55°C to 85°C			±1	
					–55°C to 125°C			±1	

Over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS				MIN	TYP	MAX	UNIT
Quiescent Device Current	I_{CC}		V_{CC} or GND	6	25°C			8	μA
					–55°C to 85°C			80	
					–55°C to 125°C			160	

(1) Any voltage between V_{CC} and GND.

9 Electrical Characteristics: HCT Devices

Over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS				MIN	TYP	MAX	UNIT
Analog Switch									
		V_{IS} (V)	V_I (V)	V_{CC} (V)	T_A				
High Level Input Voltage	V_{IH}			4.5	25°C	2			V
					–40°C to +85°C	2			
					–55°C to +125°C	2			
Low Level Input Voltage	V_{IL}				25°C			0.8	V
					–40°C to +85°C			0.8	
					–55°C to +125°C			0.8	
"ON" Resistance IO = 1mA	R_{ON}	V_{CC} or GND	V_{CC} or GND	4.5	25°C		70	160	Ω
					–40°C to +85°C			200	
					–55°C to +125°C			240	
		V_{CC} to GND	V_{CC} to GND		25°C		90	180	Ω
					–40°C to +85°C			225	
					–55°C to +125°C			270	
"ON" Resistance Between Any Two Switches	ΔR_{ON}			4.5	25°C		10		Ω
Off-Switch Leakage Current	I_Z	$\overline{E}$ = V_{CC}	V_{CC} or GND	5.5	25°C			±0.8	μA
					–55°C to 85°C			±8	
					–55°C to 125°C			±8	
Input Leakage Current (Any Control)	I_{IL}		V_{CC} or GND	5.5	25°C			±0.1	μA
					–55°C to 85°C			±1	
					–55°C to 125°C			±1	
Quiescent Device Current	I_{CC}		V_{CC} or GND	5.5	25°C			8	μA
					–55°C to 85°C			80	
					–55°C to 125°C			160	
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	▲I_{CC} (1)		V_{CC} - 2.1	4.5 to 5.5	25°C		100	360	
					–55°C to 85°C			450	
					–55°C to 125°C			490	

(1) For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA

10 HTC Input Loading

over operating free-air temperature range (unless otherwise noted)

INPUT	UNIT LOAD(1)
S_0 – S_3	0.5
$\overline{E}$	0.3

(1) Unit Load is the ΔI_{CC} limit specified in Section 9 (for example, 360-μA max at 25°C.

11 Switching Characteristics HC

over operating free-air temperature range (unless otherwise noted)

Parameter		Test Conditions		C_L (pF)	MIN	NOM	MAX	UNIT
		V_{CC} (V)	T_A					
Propagation Delay Time Switch In to Out	t_{PHL}, t_{PLH}	2	25°C	50			75	ns
			-40°C to 85°C				95	
			-55°C to 125°C				110	
		4.5	25°C				15	
			-40°C to 85°C				19	
			-55°C to 125°C				22	
		6	25°C				13	
			-40°C to 85°C				16	
			-55°C to 125°C				19	
		5	25°C	15		6		
Switch Turn On $\overline{E}$ to Out	t_{PZH}, t_{PZL}	2	25°C	50			275	ns
			-40°C to 85°C				345	
			-55°C to 125°C				415	
		4.5	25°C				55	
			-40°C to 85°C				69	
			-55°C to 125°C				83	
		6	25°C				47	
			-40°C to 85°C				59	
			-55°C to 125°C				71	
		5	25°C	15		23		
Switch Turn On Sn to Out	t_{PZH}, t_{PZL}	2	25°C	50			300	ns
			-40°C to 85°C				375	
			-55°C to 125°C				450	
		4.5	25°C				60	
			-40°C to 85°C				75	
			-55°C to 125°C				90	
		6	25°C				51	
			-40°C to 85°C				64	
			-55°C to 125°C				76	
		5	25°C	15		25		
Switch Turn Off ! E to Out	t_{PHZ}, t_{PLZ}	2	25°C	50			275	ns
			-40°C to 85°C				345	
			-55°C to 125°C				415	
		4.5	25°C				55	
			-40°C to 85°C				69	
			-55°C to 125°C				83	
		6	25°C				47	
			-40°C to 85°C				59	
			-55°C to 125°C				71	
		5	25°C	15		23		

over operating free-air temperature range (unless otherwise noted)

Parameter		Test Conditions		C_L (pF)	MIN	NOM	MAX	UNIT
Switch Turn Off Sn to Out	t_{PHZ}, t_{PLZ}	2	25°C	50			290	ns
			-40°C to 85°C				365	
			-55°C to 125°C				435	
		4.5	25°C				58	
			-40°C to 85°C				73	
			-55°C to 125°C				87	
		6	25°C				49	
			-40°C to 85°C				62	
			-55°C to 125°C				74	
		5	25°C	15		21		
Input (Control) Capacitance	C_I		25°C				10	pF
			-40°C to 85°C				10	
			-55°C to 125°C				10	
C_{PD} Power dissipation capacitance(1)	C_{PD}	5	25°C			93		

12 Switching Characteristics HCT

over operating free-air temperature range (unless otherwise noted)

Parameter		Test Conditions		C_L (pF)	MIN	NOM	MAX	UNIT
		V_{CC} (V)	T_A					
Propagation Delay Time Switch In to Out	t_{PHL}, t_{PLH}	4.5	25°C	50			15	ns
			-40°C to 85°C				19	
			-55°C to 125°C				22	
		5	25°C	15		6		
Switch Turn On $\overline{E}$ to Out	t_{PZH}, t_{PZL}	4.5	25°C	50			60	ns
			-40°C to 85°C				75	
			-55°C to 125°C				90	
		5	25°C	15		25		
Switch Turn On Sn to Out	t_{PZH}, t_{PZL}	4.5	25°C	50			60	ns
			-40°C to 85°C				75	
			-55°C to 125°C				90	
		5	25°C	15		25		
Switch Turn Off ! E to Out	t_{PHZ}, t_{PLZ}	4.5	25°C	50			55	ns
			-40°C to 85°C				69	
			-55°C to 125°C				83	
		5	25°C	15		23		
Switch Turn Off Sn to Out	t_{PHZ}, t_{PLZ}	4.5	25°C	50			58	ns
			-40°C to 85°C				73	
			-55°C to 125°C				87	
		5	25°C	15		21		

over operating free-air temperature range (unless otherwise noted)

Parameter		Test Conditions		C_L (pF)	MIN	NOM	MAX	UNIT
Input (Control) Capacitance	C_I		25°C				10	pF
			-40°C to 85°C				10	
			-55°C to 125°C				10	
C_{PD} Power dissipation capacitance(1)	C_{PD}	5	25°C			96		

13 Analog Channel Specifications

over operating free-air temperature range (unless otherwise noted)

Parameter	Test Conditions		V_{CC} (V)	HC	HCT	UNIT
Switch Frequency Response Bandwidth at -3dB			4.5	89	89	MHz
Total Harmonic Distortion	1kHz, V_{IS}= $4V_{PP}$		4.5	0.051	0.051	%
Switch "OFF" signal feedthrough			4.5	-75	-75	dB
C_I Switch input capacitance				5	5	pF
C_{COM} Common Capacitance				50	50	pF

14 Typical Characteristics

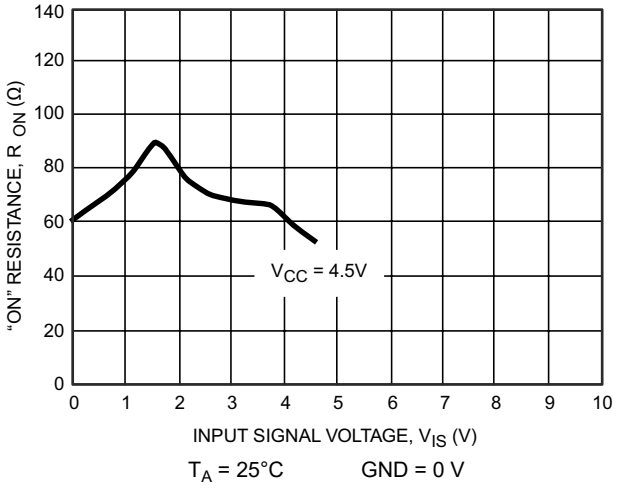


Figure 14-1. Typical ON Resistance vs Input Signal Voltage

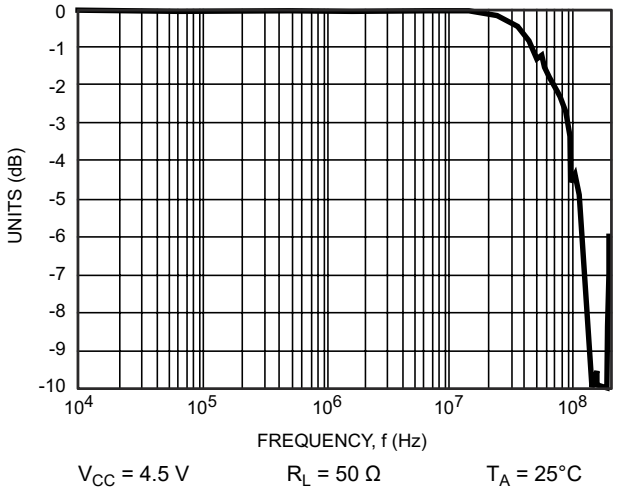


Figure 14-2. Typical Switch Frequency Response

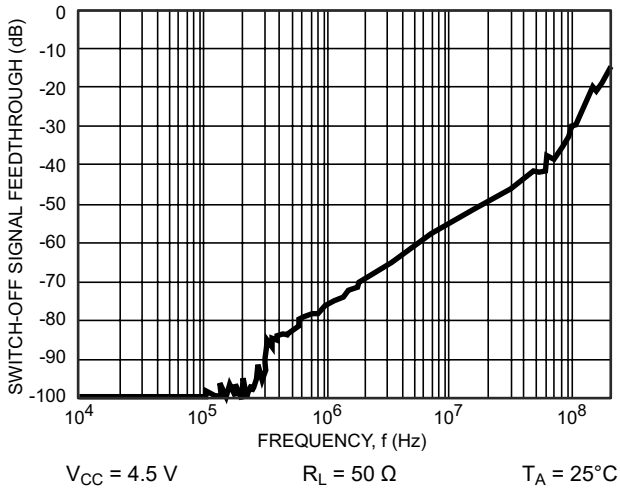


Figure 14-3. Typical Switch-Off Signal Feedthrough vs Frequency

15 Analog Test Circuits

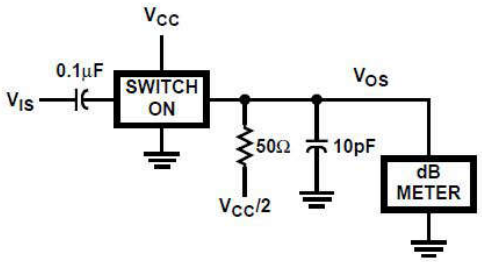


Figure 15-1. Frequency Response Test Circuit

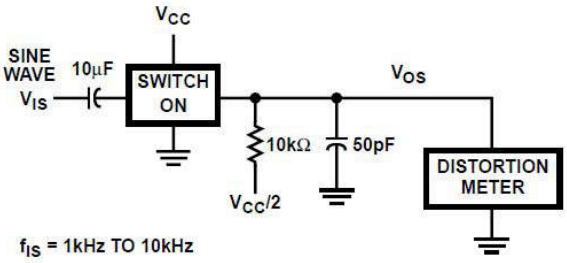


Figure 15-2. Sine Wave Distortion Test Circuit

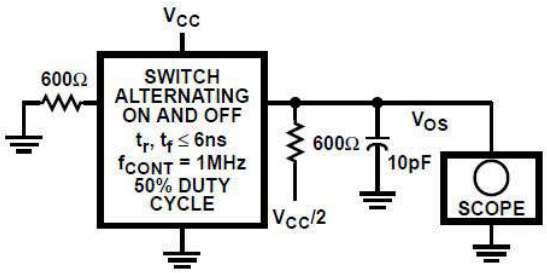


Figure 15-3. Control-to-Switch Feedthrough Noise Test Circuit

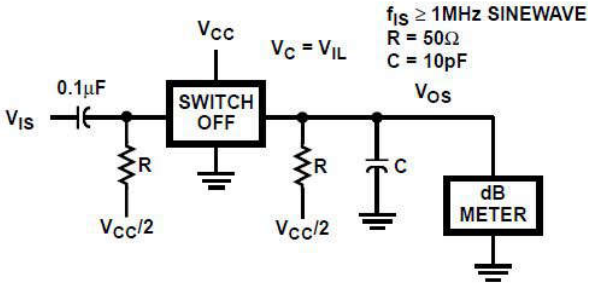


Figure 15-4. Switch Off Signal Feedthrough Test Circuit

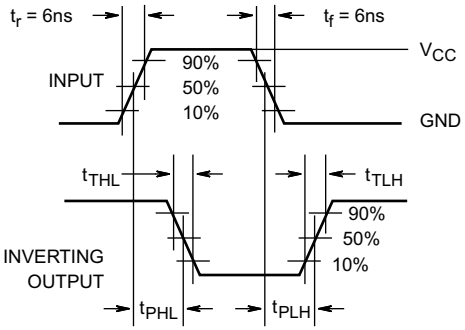


Figure 15-5. HC Transition Times and Propagation Delay Times, Combination Logic

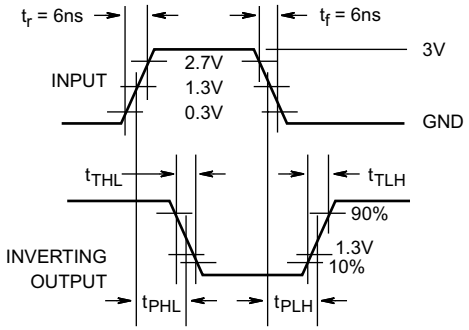


Figure 15-6. HCT Transition Times and Propagation Delay Times, Combination Logic

16 Device and Documentation Support

16.1 Related Documentation

- Texas Instruments, *High-Speed CMOS Logic 16-Channel Analog Multiplexer/Demultiplexer*

16.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

16.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

16.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

16.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

16.6 Glossary

TI Glossary — This glossary lists and explains terms, acronyms, and definitions.

17 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision C (November 2003) to Revision D (December 2024)	Page
• Updated *Applications*, *Pin Configuration and Functions* section, *ESD Ratings* table, *Thermal Information* table, *Detailed Description* section, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section	1

18 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CD74HC4067M96	Active	Production	SOIC (DW) | 24	2000 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-55 to 125	HC4067M
CD74HC4067M96.A	Active	Production	SOIC (DW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4067M
CD74HC4067PWR	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4067
CD74HC4067PWR.A	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4067
CD74HC4067RGYR	Active	Production	VQFN (RGY) | 24	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HC4067
CD74HC4067RGYR.A	Active	Production	VQFN (RGY) | 24	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-55 to 125	HC4067
CD74HC4067SM96	Active	Production	SSOP (DB) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HP4067
CD74HC4067SM96.A	Active	Production	SSOP (DB) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HP4067
CD74HC4067SM96E4	Active	Production	SSOP (DB) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HP4067
CD74HC4067SM96G4	Active	Production	SSOP (DB) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HP4067
CD74HCT4067M	Active	Production	SOIC (DW) | 24	25 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4067M
CD74HCT4067M.A	Active	Production	SOIC (DW) | 24	25 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4067M
CD74HCT4067ME4	Active	Production	SOIC (DW) | 24	25 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4067M
CD74HCT4067MG4	Active	Production	SOIC (DW) | 24	25 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4067M
CD74HCT4067PWR	Active	Production	TSSOP (PW) | 24	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HCT4067
CD74HCT4067PWR.A	Active	Production	TSSOP (PW) | 24	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4067
CD74HCT4067RGYR	Active	Production	VQFN (RGY) | 24	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HCT4067
CD74HCT4067RGYR.A	Active	Production	VQFN (RGY) | 24	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-55 to 125	HCT4067

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD74HC4067, CD74HCT4067 :

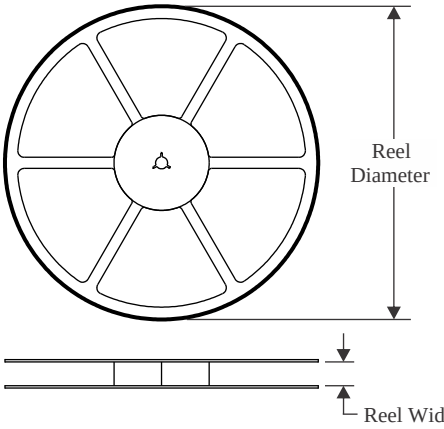
- Automotive : CD74HC4067-Q1, CD74HCT4067-Q1

NOTE: Qualified Version Definitions:

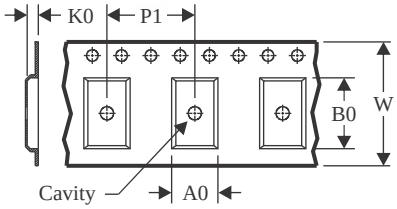
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

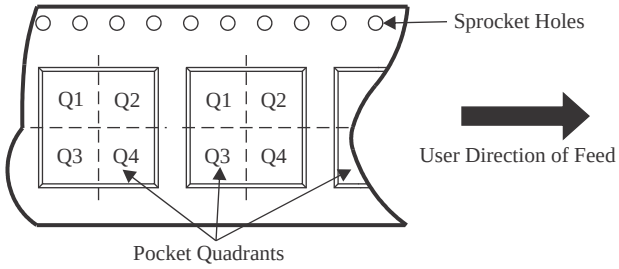


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

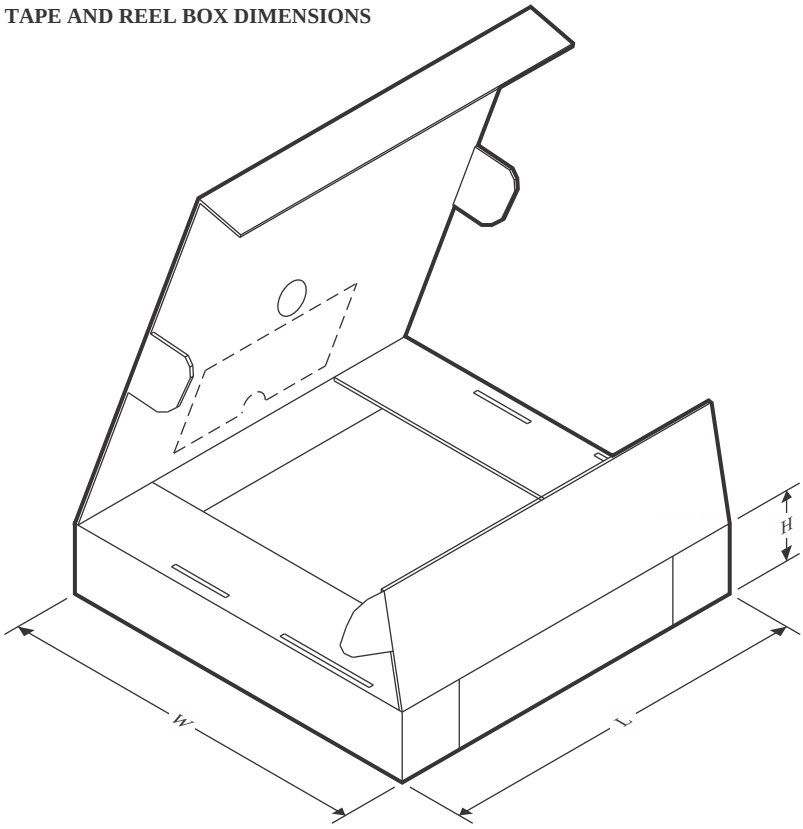
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC4067M96	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
CD74HC4067PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
CD74HC4067RGYR	VQFN	RGY	24	3000	330.0	12.4	3.8	5.8	1.2	8.0	12.0	Q1
CD74HC4067SM96	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
CD74HC4067SM96	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
CD74HCT4067PWR	TSSOP	PW	24	3000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
CD74HCT4067RGYR	VQFN	RGY	24	3000	330.0	12.4	3.8	5.8	1.2	8.0	12.0	Q1

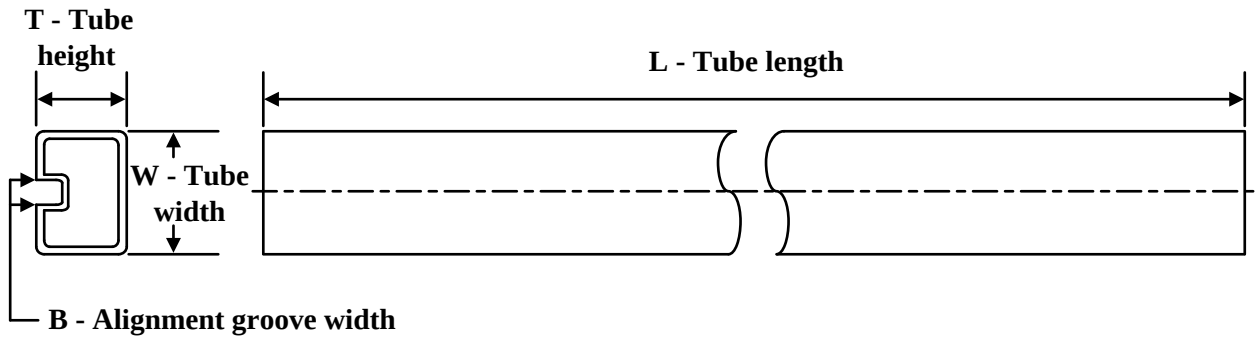
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC4067M96	SOIC	DW	24	2000	350.0	350.0	43.0
CD74HC4067PWR	TSSOP	PW	24	2000	356.0	356.0	35.0
CD74HC4067RGYR	VQFN	RGY	24	3000	367.0	367.0	35.0
CD74HC4067SM96	SSOP	DB	24	2000	353.0	353.0	32.0
CD74HC4067SM96	SSOP	DB	24	2000	356.0	356.0	35.0
CD74HCT4067PWR	TSSOP	PW	24	3000	356.0	356.0	35.0
CD74HCT4067RGYR	VQFN	RGY	24	3000	367.0	367.0	35.0

TUBE



*All dimensions are nominal

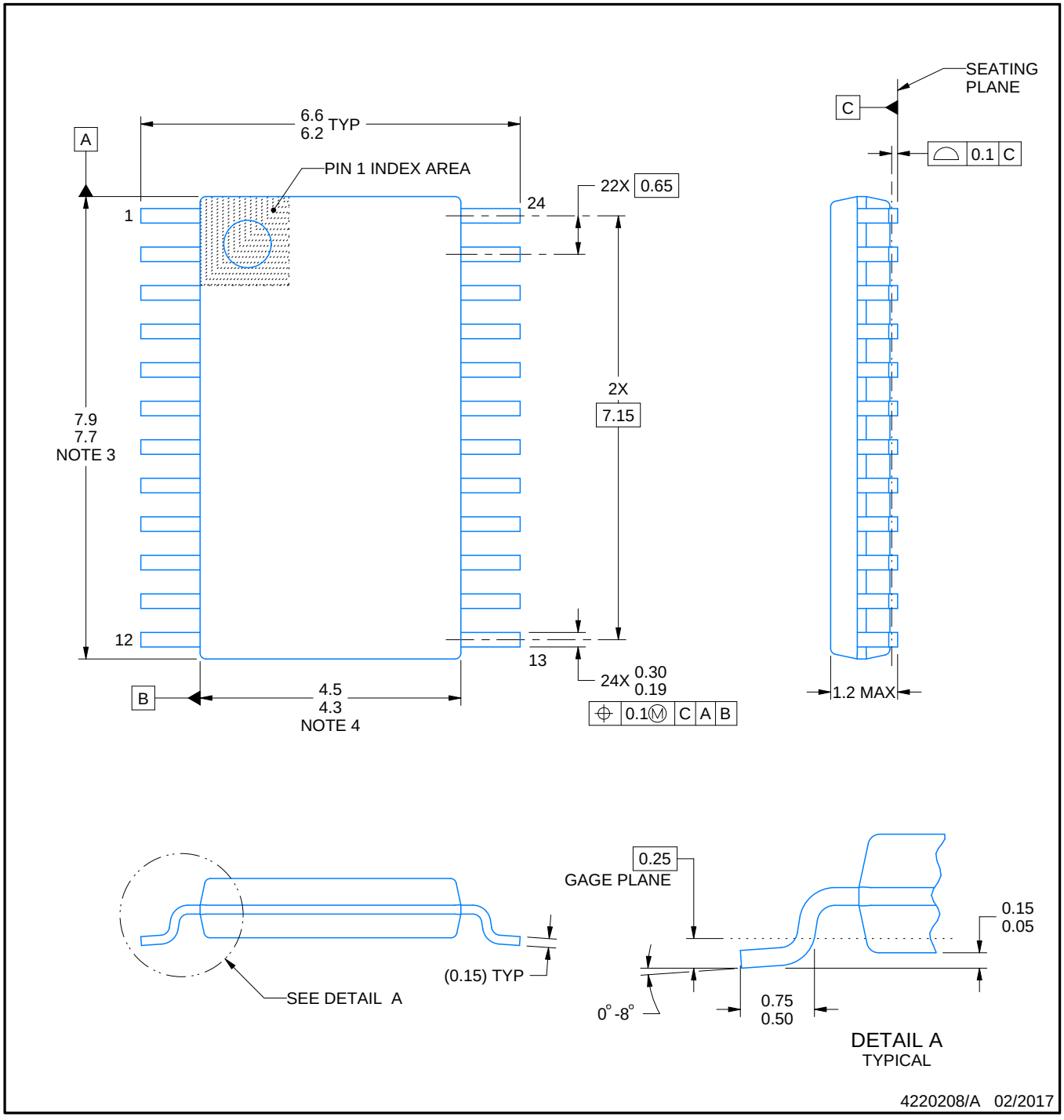
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74HCT4067M	DW	SOIC	24	25	506.98	12.7	4826	6.6
CD74HCT4067M.A	DW	SOIC	24	25	506.98	12.7	4826	6.6
CD74HCT4067ME4	DW	SOIC	24	25	506.98	12.7	4826	6.6
CD74HCT4067MG4	DW	SOIC	24	25	506.98	12.7	4826	6.6

PACKAGE OUTLINE

PW0024A

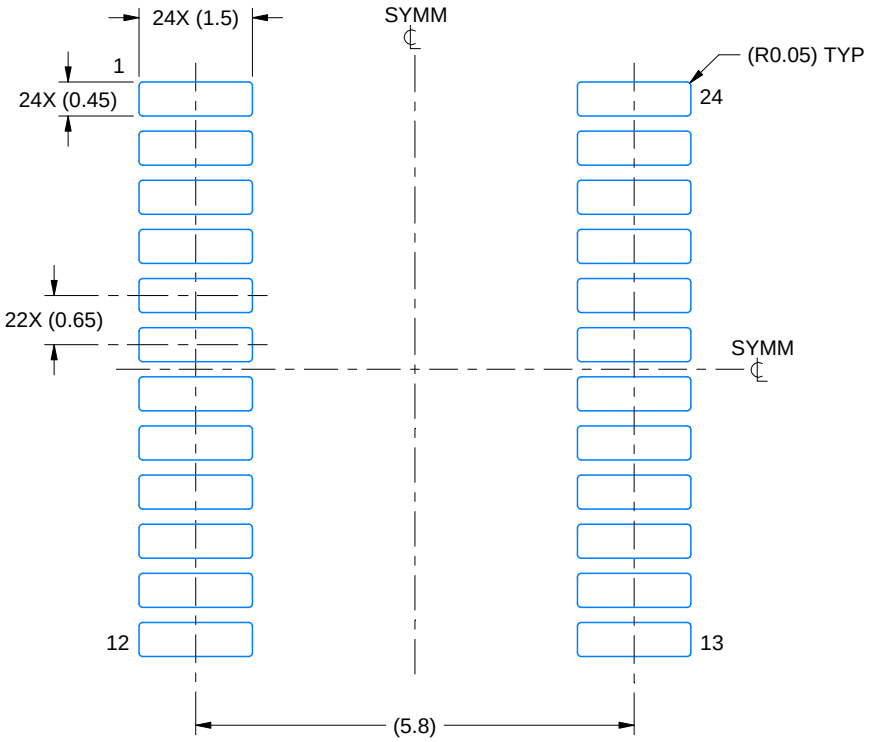
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

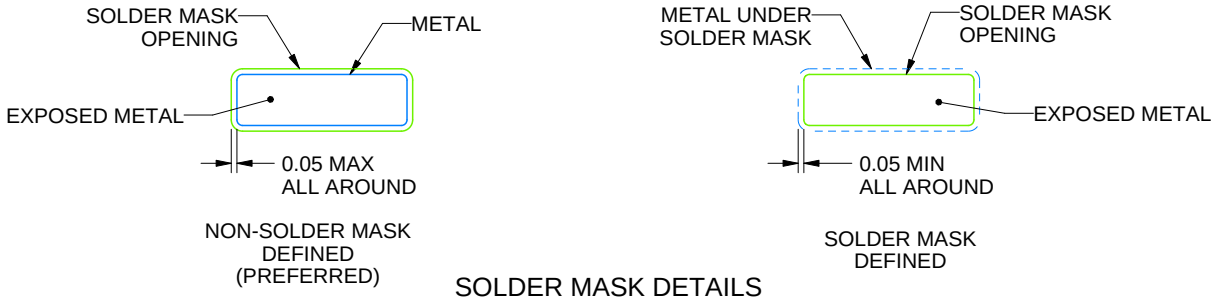


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

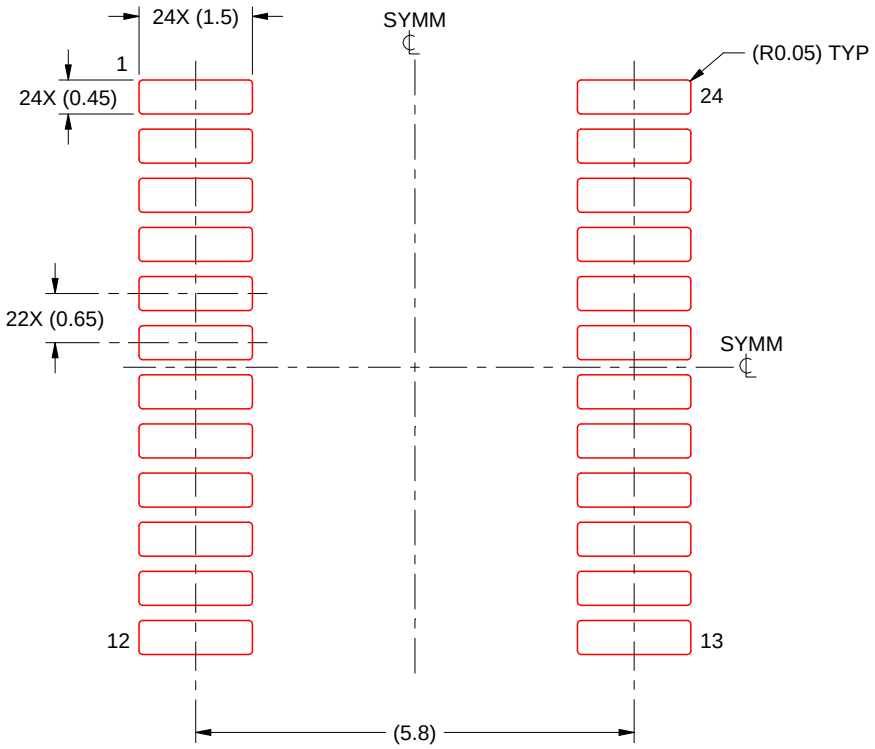


SOLDER MASK DETAILS

4220208/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



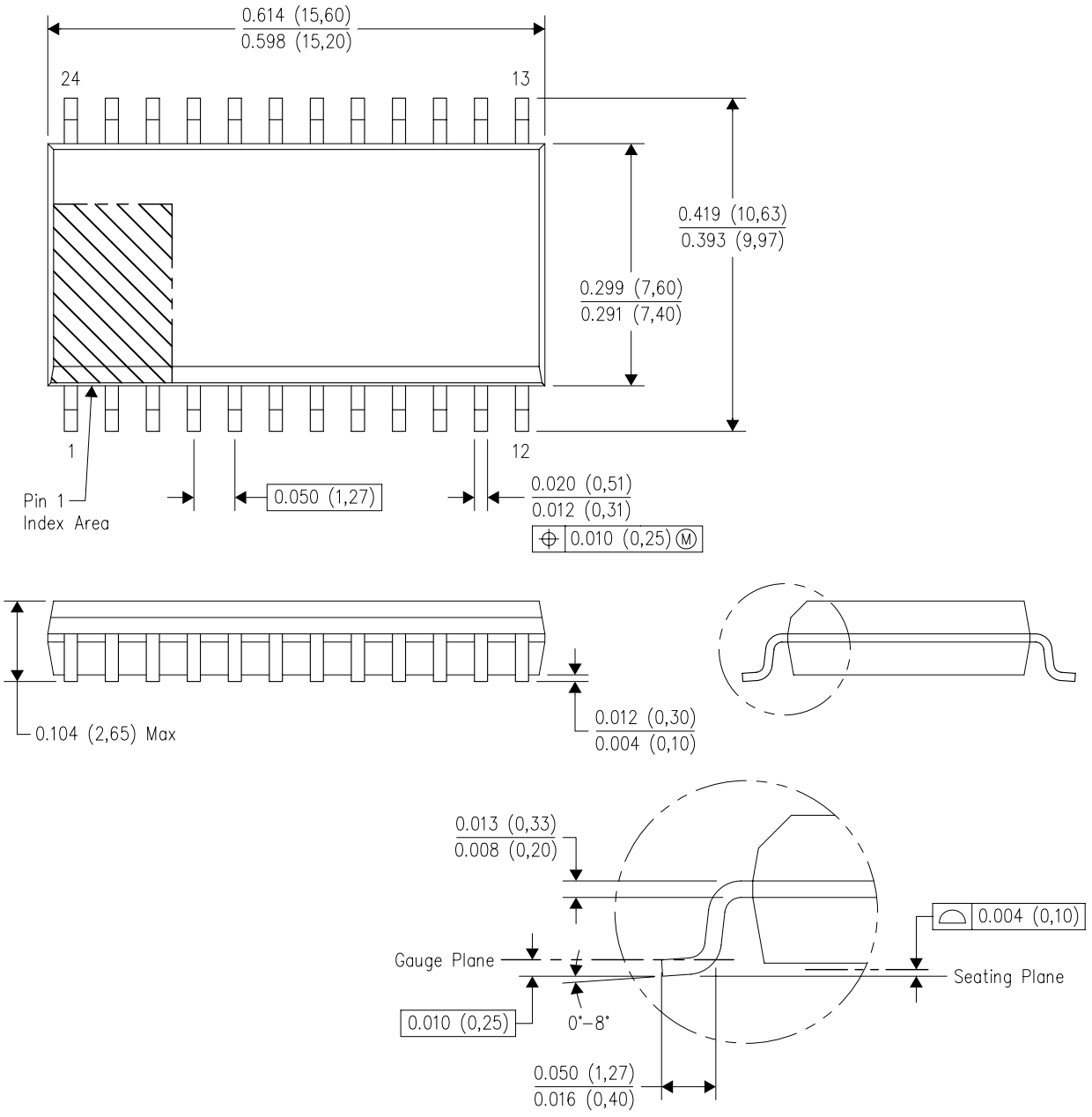
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

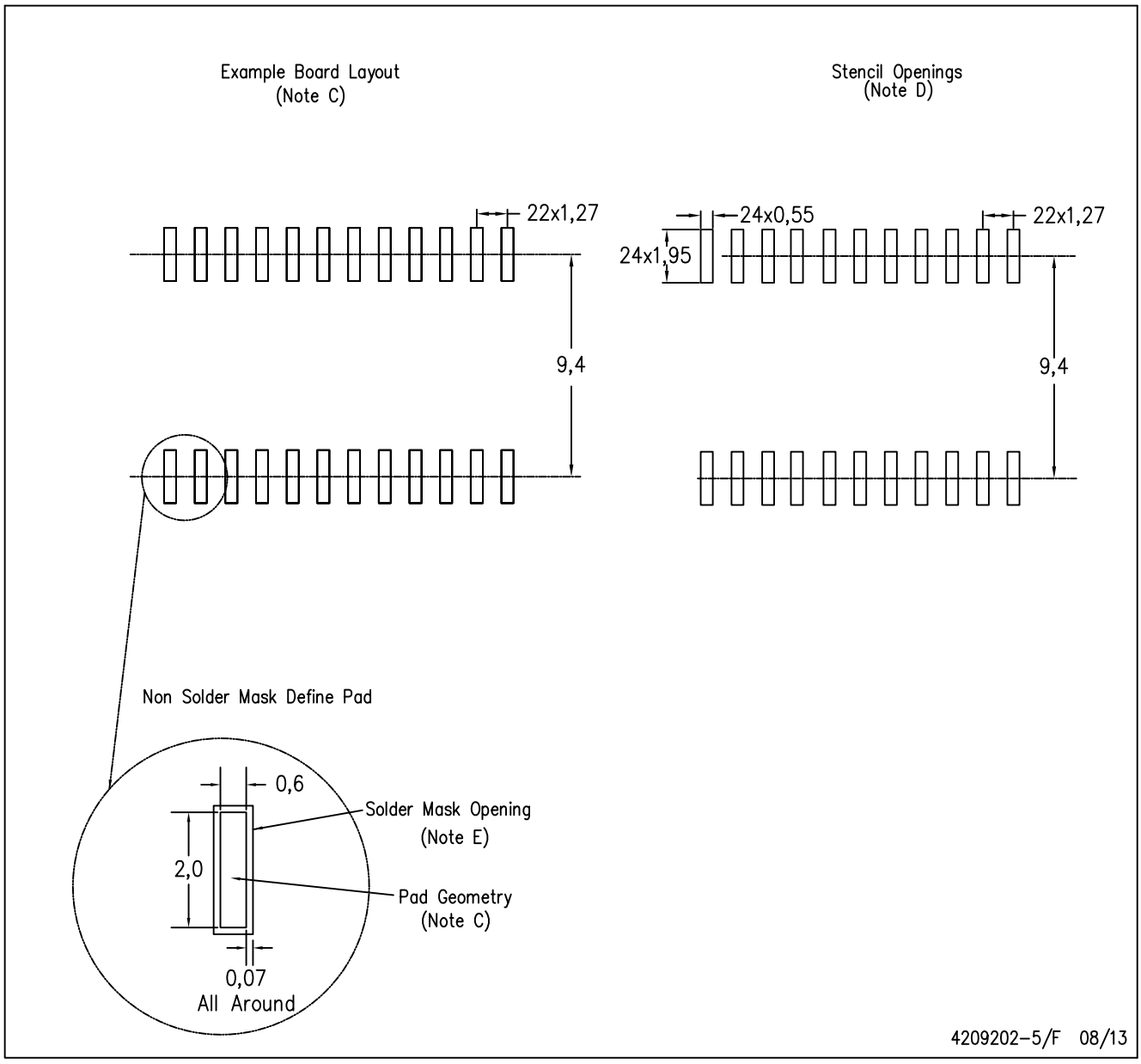
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DW (R–PDSO–G24) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AD.

DW (R–PDSO–G24) PLASTIC SMALL OUTLINE

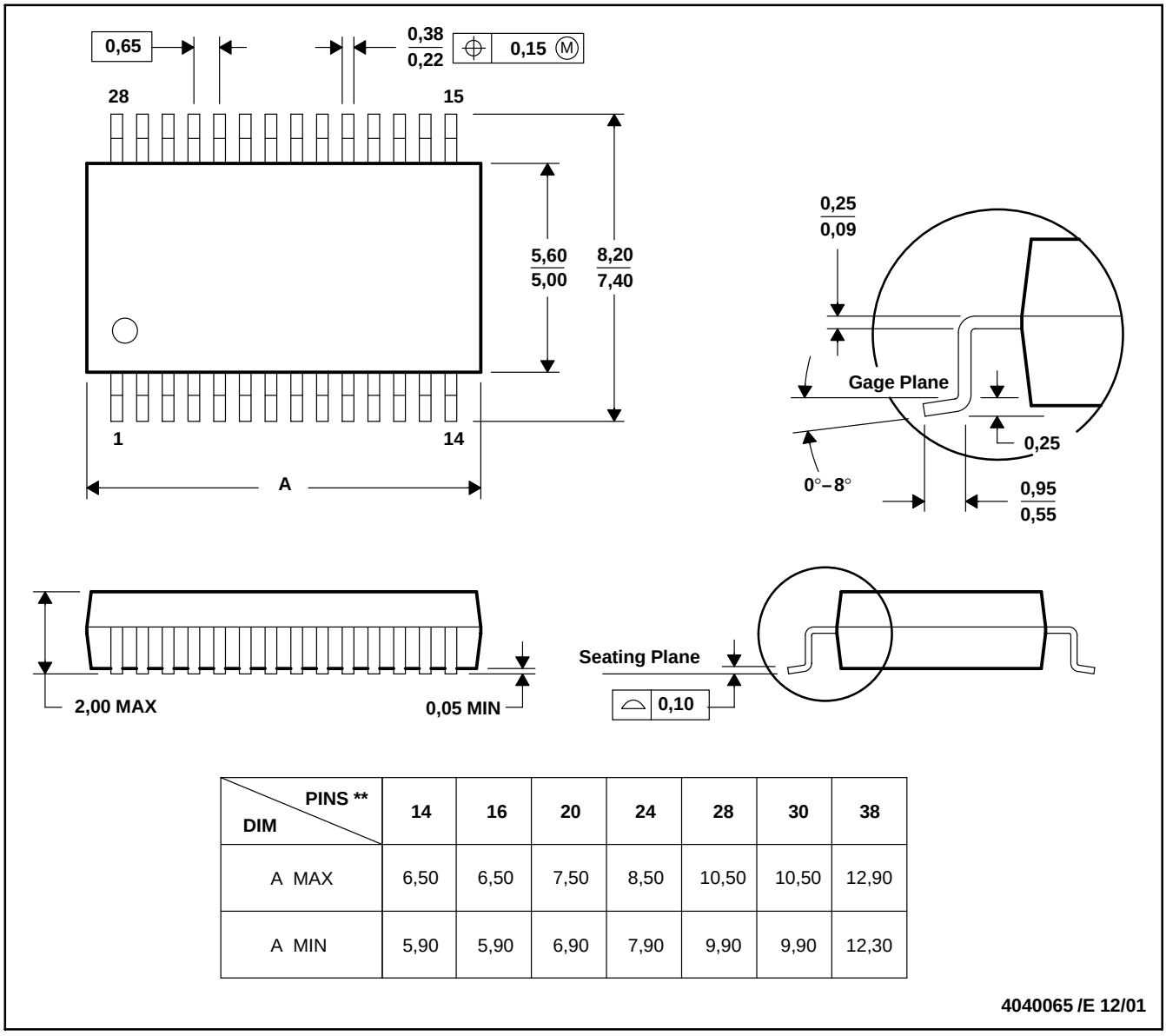


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Refer to IPC7351 for alternate board design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

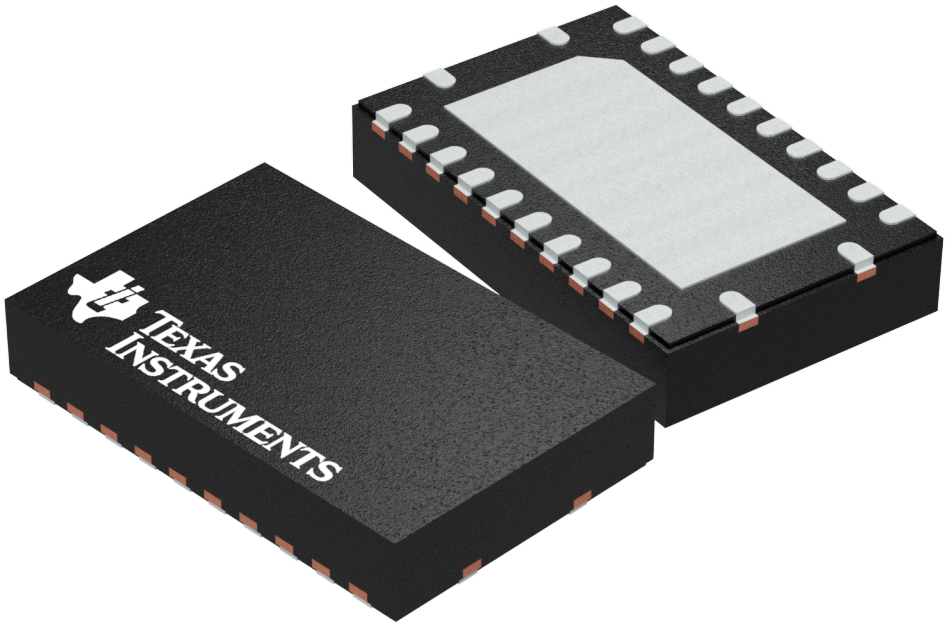
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

RGY 24

VQFN - 1 mm max height

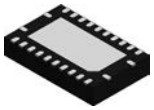
5.5 x 3.5 mm, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

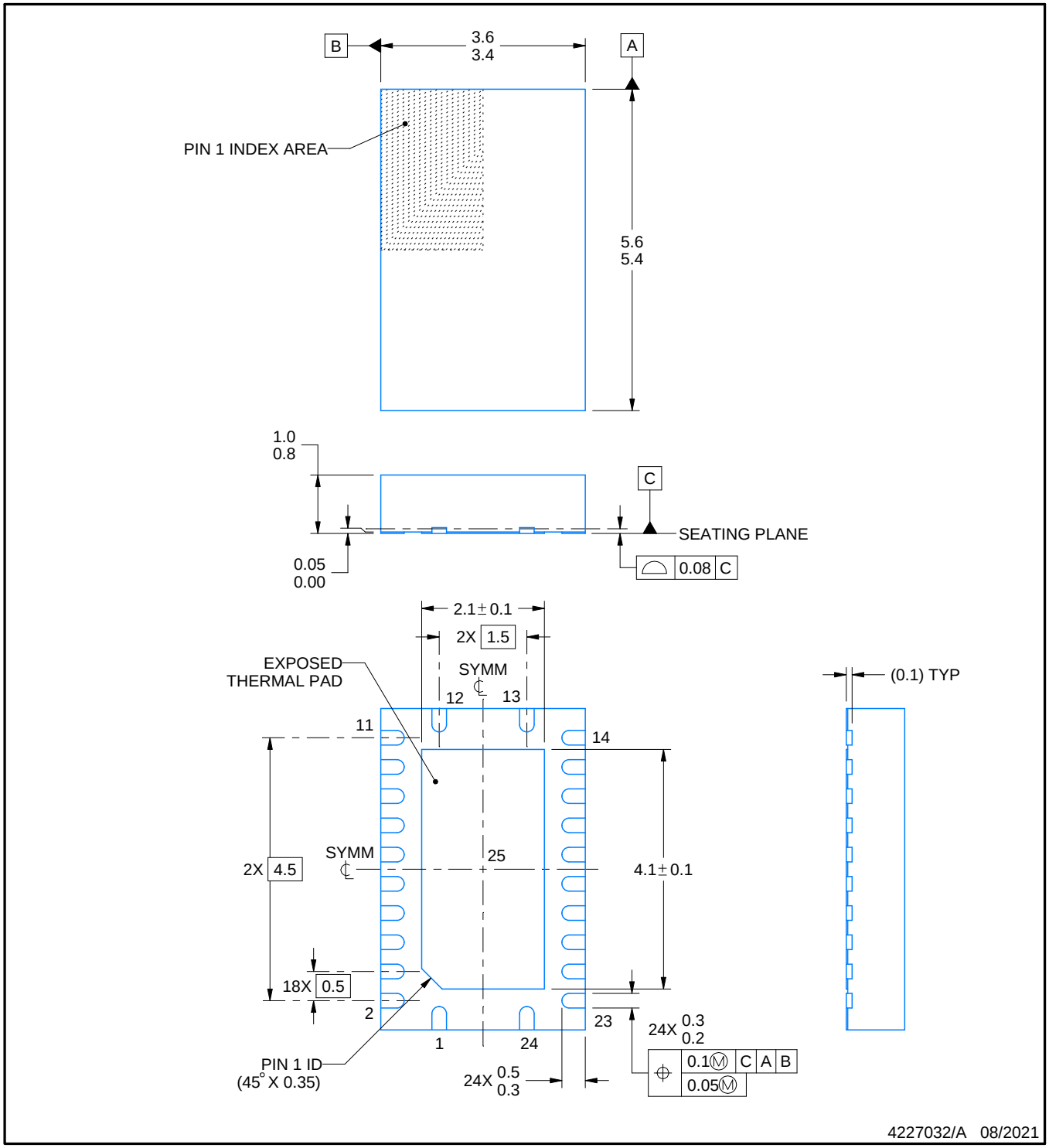
RGY0024F



PACKAGE OUTLINE

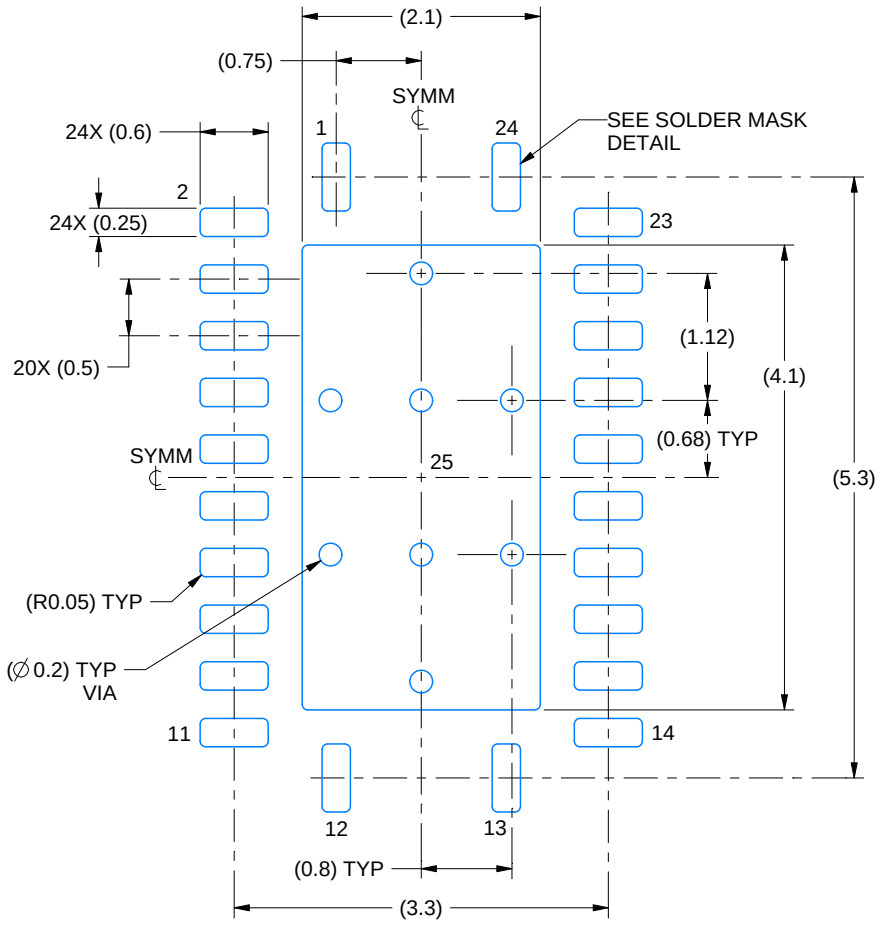
VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

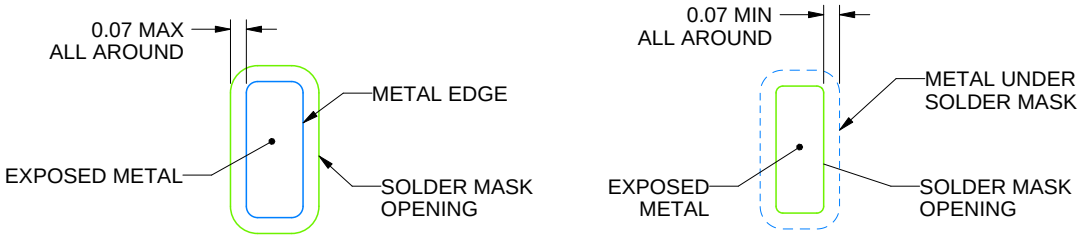


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X

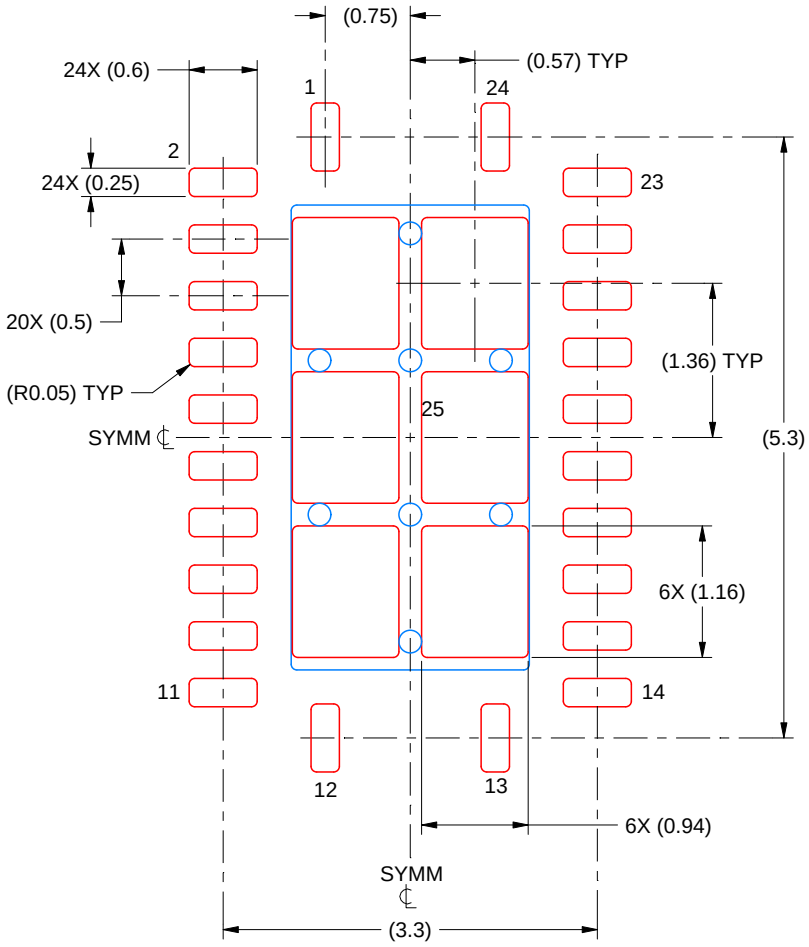


SOLDER MASK DETAILS

4227032/A 08/2021

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 15X

EXPOSED PAD 25
76% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

4227032/A 08/2021

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265